

*A<sub>2</sub>*  
Page 3, between lines 10 and 12, insert

--- Summary of the Invention: ---;

*A<sub>3</sub>*  
Page 11, before line 1, insert

--- Brief Description of the Drawing:

Fig. 1 shows a cross sectional view of the layers of a component.

*A<sub>4</sub>*  
Description of the Preferred Embodiment: ---.

Page 17, top, change "Patent claims" to -- We Claim: ---.

*A<sub>4</sub>*  
Page 18, top, change "Abstract" to -- Abstract of the Disclosure: ---; and

Page 18, line 9, delete the paragraph reading, "FIG 1".

In the Claims:

Cancel claims 1-3 and enter the following new claims.

*A<sub>5</sub>*  
--- 4. A process for metallizing at least one insulating layer of an electronic or microelectronic component, which comprises:

*Sub 1*  
applying at least one first insulating layer to a substrate such that the first insulating layer has a thickness not greater than 50 $\mu$ m;